SK 10 BGD 065 ET



SEMITOP[®] 3

1-phase bridge rectifier + 3-phase bridge inverter

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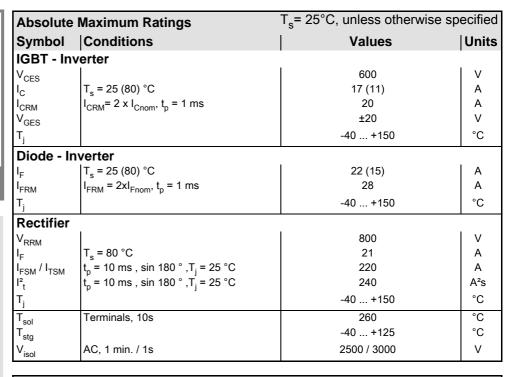
Target Data

Features

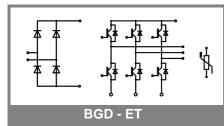
- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded alumium oxide ceramic (DCB)
- Ultrafast NPT technology IGBT
- CAL Technology FWD
- Integrated NTC temperature sensor

Typical Applications*

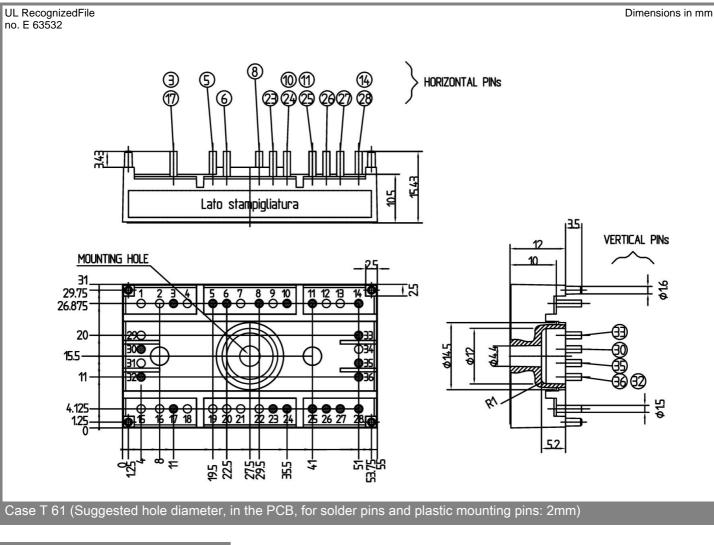
Inverter

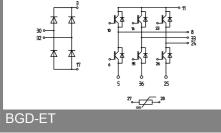


Characteristics		T _s = 25°C	T_s = 25°C, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units	
IGBT - Inverter						
V _{CEsat} V _{GE(th)} V _{CE(TO)} r _T C _{ies}	$ \begin{vmatrix} I_{C} = 6 \text{ A}, T_{j} = 25 (125) \text{ °C} \\ V_{GE} = V_{CE}, I_{C} = 0,5 \text{ mA} \\ T_{j} = 25 \text{ °C} (125) \text{ °C} \\ T_{j} = 25 \text{ °C} (125) \text{ °C} \\ V_{CE} = 25 V_{GE} = 0 \text{ V}, f = 1 \text{ MHz} $	3	2 (2,3) 4 1,2 (1,1) 133 (183) 0,5	2,5 5 1,3 200	V V mΩ nF	
C _{oes} C _{res} R _{th(j-s)}	$V_{CE} = 25 V_{GE} = 0 V$, f = 1 MHz $V_{CE} = 25 V_{GE} = 0 V$, f = 1 MHz per IGBT		0,1 0,1	2	nF nF K/W	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	under following conditions $V_{CC} = 300 \text{ V}, V_{GE} = \pm 15 \text{ V}$ $I_C = 6 \text{ A}, T_j = 125 \text{ °C}$ $R_{Gon} = R_{Goff} = 210 \Omega$ inductive load		45 30 340 25 0,18 0,13		ns ns ns mJ mJ	
Diode - Ir	verter	1				
$V_F = V_{EC}$ $V_{(TO)}$ r_T $R_{th(j-s)}$	$T_j = 25 °C (125) °C$ $T_j = 25 °C (125) °C$ per diode		1,3 (1,2) 1 (0,9) 45 (50)	1,5 1,1 60 2,3	V V mΩ K/W	
I _{RRM} Q _{rr} E _{rr}	under following conditions $I_F = 6 A, V_R = 300 V$ $V_{GE} = 0 V, T_j = 125 °C$ $di_{F/dt} = 170 A/\mu s$		8,4 0,8 0,18		Α μC mJ	
Diode rec	tifier					
V _F V _(TO) r _T R	$ I_F = 15 \text{ A}, T_j = 25() ^{\circ}\text{C}$ $T_j = 150 ^{\circ}\text{C}$ $T_j = 150 ^{\circ}\text{C}$ per diode		1,1 0,8 20	2,7	V V mΩ K/W	
R _{th(j-s)}				۲,۲	1.7.4.4	
R _{ts}	t ur sensor 5 %, T _r = 25 (100) °C	1	5000(493)		Ω	
Mechanic					1 ==	
w M _s	Mounting torque		30	2,5	g Nm	



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.